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ABSTRACT

PROCESS FOR PRODUCTION OF EPOXY RESIN COMPOSITION FOR SEMICONDUCTOR ENCAPSULATION, EPOXY RESIN COMPOSITION FOR SEMICONDUCTOR ENCAPSULATION, AND SEMICONDUCTOR DEVICE

The present invention provides a process for producing an epoxy resin composition for semiconductor encapsulation which, when used in encapsulation of a semiconductor chip, can minimize voids appearing in the semiconductor device obtained. That is, the present invention provides a process for producing an epoxy resin composition for semiconductor encapsulation, which comprises premixing raw materials containing at least an epoxy resin, a phenolic resin, a curing accelerator and an inorganic filler, then grinding the resulting premix using a grinder to obtain a ground material having such a particle size distribution that particles having particle diameters of 250 μm or more are 10% by weight or less, particles having particle diameters of 150 μm to less than 250 μm are 15% by weight or less and particles having particle diameters of less than 150 μm are 75% by weight or more, and melt-kneading the ground material under a reduced pressure, or melt-kneading the ground material and then exposing the resulting molten material to a reduced pressure.